

1       **DECLARATION OF CONTINUATION-IN-PART FOR PATENT APPLICATION**

2           As a below named inventor, I hereby declare that:

3           My residence, post office address and citizenship are as stated  
4 below next to my name.

5           I believe I am the original, first and joint inventor of the subject  
6 matter which is claimed and for which a patent is sought on the  
7 invention entitled: Semiconductor Processing Methods of Forming  
8 Photoresist Over Silicon Nitride Materials, and Semiconductor Wafer  
9 Assemblies Comprising Photoresist Over Silicon Nitride Materials,  
10 identified as U.S. Patent Application Serial No. 09/457,093, filed on  
11 December 7, 1999.

12           This application in part discloses and claims subject matter  
13 disclosed in my earlier filed pending application, Semiconductor  
14 Processing Methods of Forming Photoresist Over Silicon Nitride  
15 Materials, and Semiconductor Wafer Assemblies Comprising Photoresist  
16 Over Silicon Nitride Materials, Serial No. 09/057,155, filed April 7, 1998;

17           This application in part also discloses and claims subject matter  
18 disclosed in my earlier filed pending application, Semiconductor  
19 Processing Method of Promoting Photoresist Adhesion to an Outer  
20 Substrate Layer Predominately Comprising Silicon Nitride, Serial No.  
21 09/295,642, filed April 20, 1999;

**EL 979950548**

PAT-USDE-03

**EL 844051467**

1 I hereby state that I have reviewed and understand the contents  
2 of the above identified specification, including the claims.

3 I hereby claim benefit under Title 35, United States Code, §120  
4 in connection with said earlier filed applications;

5 I acknowledge the duty to disclose information known to me to be  
6 material to patentability as defined in Title 37, Code of Federal  
7 Regulations §1.56, including any such information which became available  
8 between the filing dates of the prior applications and the national or  
9 PCT international filing date of this application.

10 As to the subject matter of this application which is common to  
11 said earlier applications, I do not know and do not believe that the  
12 same was ever known or used in the United States of America before  
13 our invention thereof or patented or described in any printed publication  
14 in any country before our invention thereof, or more than one year prior  
15 to said earlier applications, or in public use or on sale in the United  
16 States of America more than one year prior to said earlier applications;

17 The common subject matter has not been patented or made the  
18 subject of an inventor's certificate issued before the dates of said earlier  
19 applications in any country foreign to the United States of America on  
20 an application filed by me or my legal representatives or assigns more  
21 than twelve months prior to said earlier applications; and  
22

1 As to applications for patents or inventor's certificate on the  
2 common subject matter filed in any country foreign to the United States  
3 of America, prior to said earlier applications by me or my legal  
4 representatives or assigns, I hereby claim foreign priority benefits under  
5 Title 35, United States Code, §119 of any foreign application(s) for  
6 patent or inventor's certificate listed below and have also identified below  
7 any foreign application for patent or inventor's certificate having a filing  
8 date before those of the applications on which priority is claimed:

9 PRIOR FOREIGN APPLICATION(S)

10 No such applications have been filed.  
11

12 As to the subject matter of this application which is not common  
13 to said earlier applications, I do not know and do not believe that the  
14 same was ever known or used in the United States of America before  
15 our invention thereof or patented or described in any printed publication  
16 in any country before our invention thereof, or more than one year prior  
17 to this application, or in public use or on sale in the United States of  
18 America more than one year prior to this application;

19 Said non-common subject matter has not been patented or made  
20 the subject of an inventor's certificate issued before the date of this  
21 application in any country foreign to the United States of America on  
22

1 an application filed by me or my legal representatives or assigns more  
2 than twelve months prior to this application; and

3 As to applications for patents or inventor's certificate on the  
4 invention filed in any country foreign to the United States of America  
5 prior to this application by me or my legal representatives or assigns, I  
6 hereby claim foreign priority benefits under Title 35, United States Code,  
7 §119 of any foreign application(s) for patent or inventor's certificate  
8 listed below and certificate having a filing date before those of the  
9 applications on which priority is claimed:

10 PRIOR FOREIGN APPLICATION(S)

11 No such applications have been filed.  
12

13 I hereby declare that all statements made herein of my own  
14 knowledge are true and that all statements made on information and  
15 belief are believed to be true; and further that these statements were  
16 made with the knowledge that willful false statements and the like so  
17 made are punishable by fine or imprisonment, or both, under  
18 Section 1001 of Title 18 of the United States Code and that such willful  
19 false statement may jeopardize the validity of the application or any  
20 patent issued therefrom.  
21  
22

\* \* \* \* \*

Full name of inventor: John T. Moore

Inventor's Signature: John T. Moore

Date: 10/30/00

Residence: Boise, ID

Citizenship: U.S.

Post Office Address: 12530 W. Lexus Ct.  
Boise, ID 83713

\* \* \* \* \*

Full name of inventor: Scott Jeffrey DeBoer

Inventor's Signature: Scott J DeBoer

Date: 10/30/00

Residence: Boise, ID

Citizenship: U.S.

Post Office Address: 259 E. Twin Willow  
Boise, ID 83706

\* \* \* \* \*

Full name of inventor: Mark Fischer

Inventor's Signature: Mark Fischer

Date: 10/30/00

Residence: Boise, ID

Citizenship: U.S.

Post Office Address: 11485 W. Puritan Drive  
Boise, ID 83709

\* \* \* \* \*

Full name of inventor: J. Brett Rolfson

Inventor's Signature: J. Brett Rolfson

Date: 10/31/00

Residence: Boise, ID

Citizenship: U.S.

Post Office Address: P.O. Box 15537  
Boise, ID 83715

\*\*\*\*\*

Full name of inventor: Annette L. Martin

Inventor's Signature: Annette L. Martin

Date: Oct 11, 2000

Residence: Boise, ID

Citizenship: U.S.

Post Office Address: 10576 Dason Drive  
Boise, ID 83704

\*\*\*\*\*

Full name of inventor: Ardavan Niroomand

Inventor's Signature: Ardavan Niroomand

Date: 10/30/2000

Residence: Boise, ID

Citizenship: U.S.

Post Office Address: 4338 S. Rimview  
Boise, ID 83705